OPTO-ELECTRONIC MODULES AND METHODS OF MANUFACTURING THE SAME ~~AND APPLIANCES AND DEVICES COMPRISING THE SAME~~

Technical Field

The invention relates to the field of opto-electronics and more specifically to the packaging and manufacturing of opto-electronic components. More particularly, it relates to opto-electronic modules and to methods of manufacturing the same and to appliances and to electronic devices comprising such modules, in particular wherein the modules comprise at least one light detector. The invention relates to methods and apparatuses according to the opening clauses of the claims.

Background of the Invention

From US 2010/0327164 A1, an opto-electronic module, more specifically a proximity sensor is known, during the manufacture of which light emitter dice and light detector dice are overmolded using transfer molding techniques so as to form lenses on these dice.

In US 5,912,872, an integrated optical apparatus is presented. In the manufacture thereof, a support wafer having a plurality of active elements thereon is aligned with a